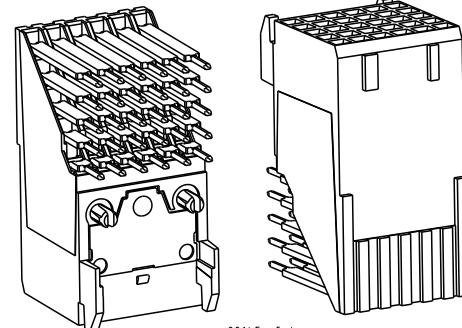


TIN LEAD PRODUCT NUMBER	ROW	CONFIGURATION					
		6	5	4	3	2	1
52085-X01(LF)	E	X	X	X	X	X	X
A performance (see table) loading pattern	D	X	X	X	X	X	X
Lead Free designation	C	X	X	X	X	X	X
	B	X	X	X	X	X	X
	A	X	X	X	X	X	X

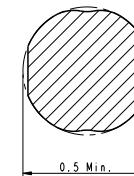
"—" POSITION NOT LOADED
"-X" POSITION LOADED

PRODUCT NUMBER	MATING PERFORMANCE LEVEL
52048-101(LF)	STANDARD P/N - TELCORDIA CO Compatible
52048-301(LF)	CUSTOMER SPECIFIC
52048-E01(LF)	CUSTOMER SPECIFIC

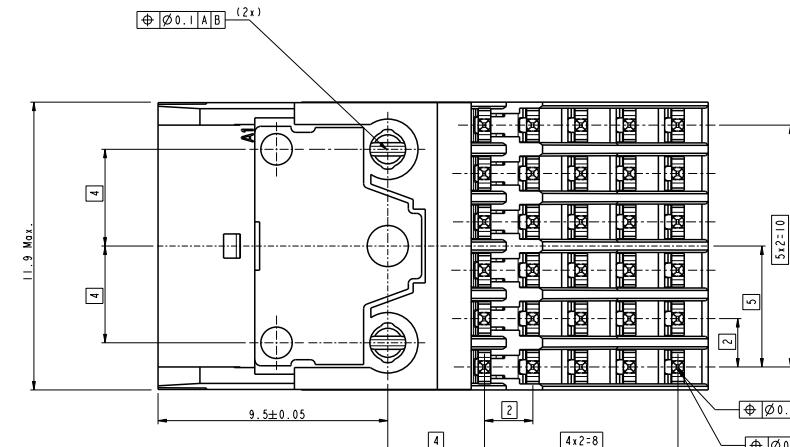
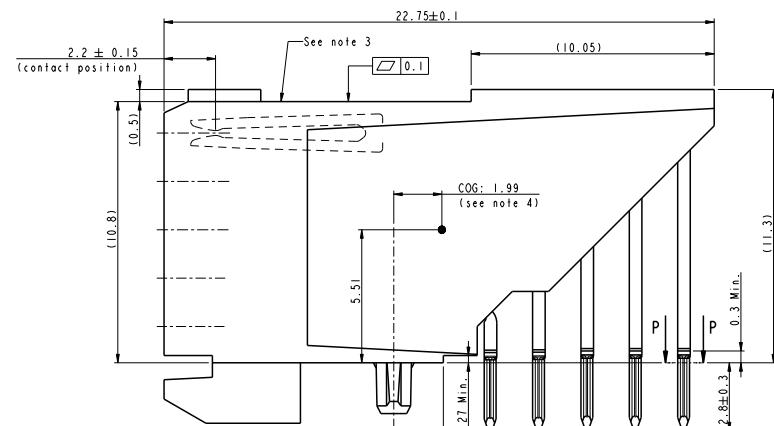
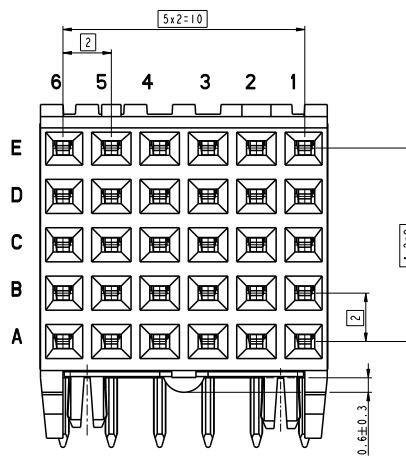
This technical drawing shows a cross-sectional view of a vacuum device assembly. The overall width is 11.55 Max. (note 7). A central circular area is labeled "AREA SUITABLE FOR VACUUM DEVICE". The drawing includes several dimensions: 4±0.1 on the left, 6±0.1 at the bottom right, and 9.7 Min. on the right edge. The assembly consists of a central circular component with a flange, surrounded by a housing with various ports and a base plate.



SCALE 5



SECTION P-P
SCALE 100:1



NOTES:

NOTES:

1. Housing material: Liquid Cristal Polymer 30% glass, flame retardant according to UL 94-V0. Contact material phosphor bronze.
2. All solder surfaces are tin or tin-alloy plated.
3. Product marking on indicated surface: part number and manufacturing code. It will not prevent picking up with a vacuum device.
4. Center of gravity of indicated point. Mass of product 5.65 g.
5. Maximum mounting force per connector 20N on bare board.
6. This dimension shows maximum position of the centre of the vacuum nozzle. Recommended position is 9.5 mm in line with the pegs.
7. The connector is tape-and-reel packed according to GS-14-626, which follows EIA-481B. Tape width 44 mm, cavity pitch 20 mm. The tape has recesses at the sides to allow use of gripper.
8. Product specification according to GS-12-215.
9. For pin-in-paste recommendation, see sheet 2 and application guide GS-20-024.

10. RoHS INFORMATION:

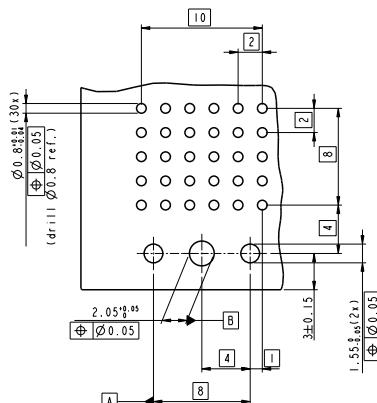
- The "LF" products meet European Union Directives and other country regulations as described in GS-22-008
- The housing will withstand exposure to 260°C peak temperature for 30 seconds in a convection, infra-red or vapor reflow oven. See application notes/procedures if they are available.
- Termination plating spec: 1.27µm Ni mini, 2.5 to 7.5µm Sn (pure matte)
- Packaging spec: see GS-14-920

Material		Spec ref	
Mat code		surface	Tolerance
Heat treat		ISO 406	projection
Piping/finish		ISO 1302	ISO 1101
Dr. P Poirier	2002/04/23		mm
Eng P Poirier	2002/04/23	Product family	size
Chr P Poirier	2002/04/22	Model Name	Scale
Appl P Poirier	2002/04/23	Model Revision	10:1
D L 4666	ME 2004/01/17/00	5x6 RA Assy	
E LOS5-302	LMA 2005/01/17/00	Signal RCP PIP with HDF	
F 3007-004	ME 2007/02/17/00		
G 3007-010	ME 2008/02/17/00		
Profit file catalog no		material	customer copy
sheet 1 of 2			

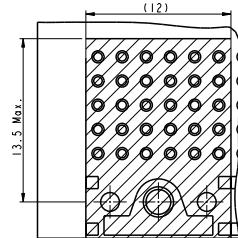
All items mentioned on this sheet are recommendations of FCI and should be seen as indication. The final responsibility for the application process is at the customer.

PCB LAYOUT: HOLE PATTERN

PCB thickness 1.4 - 2.6 mm.

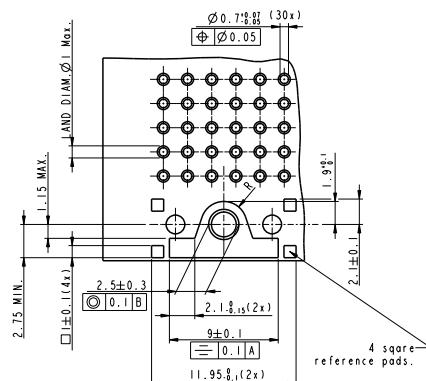


PCB LAYOUT: BOARD AREA



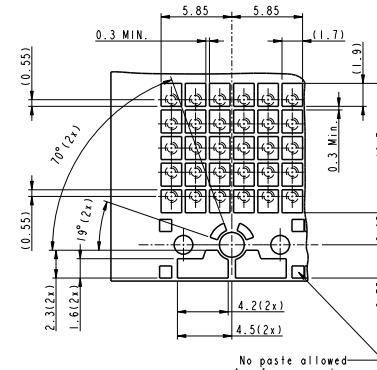
PCB LAYOUT: PLATING

Plating thickness must be constant over the connector area. Copper layer 50 μm max. Solder mask should cover all surfaces under the paste that are not plated. There is no solder mask allowed on the reference pads.



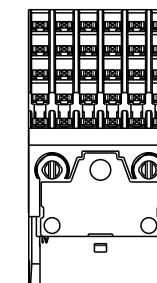
PCB LAYOUT : SOLDER PASTE

Recommended stencil thickness 0.15 mm.
The solder content in the paste should be sufficient, typically 50% volume percentage.
The solder foil, PCB, stencil and application process determine the solder result. The squeegee process (angle, speed, pressure, material and number of cycles) must be optimized, so that sufficient solder is available.



CONNECTOR MOUNTING

The connector can be picked up with a mechanical gripper or a vacuum nozzle. Nozzle diameter 6 - 10 mm. Both metal nozzles or nozzles with seal or rubber can be used. Vacuum pressure 0.6 bar under local ambient pressure. Position of the nozzle on the connector as mentioned on sheet 1. The reference for placing the connector can be determined by video inspection of the connector bottomside. The recesses of the retention pegs are designed for video recognition (shown bold, see sketch below). The line through the center of the recesses is the reference for Y-direction and rotation; datum **[B]**. The line through the middle between the center of the recesses perpendicular to the first line is reference for X-direction; datum **[A]**.



The acceleration and the deceleration of the mounting head of the pick and place equipment should be restricted in such a way that the connector doesn't fall off or slides on the nozzle. An inferior accuracy of the placing equipment can reduce the success rate of mounting. The last movement of the connector must be purely vertical and downwards. The board must be horizontal. The final mounting force must be controlled in such a way that the connector is seated flush to the board and remains there after releasing from the placing device. (Extra) PCB support can be required to meet this. The movement of the PCB assembly before reflowing must be smooth so that all components remain seated flush on the board.

Material	-	Spec ref	
Matl Code	-	surface	projection
Headtail	-	ISO 1302	mm
Part/Finish	-	ISO 406 ISO 1101	
Dr. P. Poller	2002/04/23		Line
Eng. P. Poller	2002/04/23	Product family	Scale
Chr. P. Poller	2002/04/23	Model / Name	AI
		52085	S-1
Aper. P. Poller	2002/04/23	Model / Revision	ECN
			LS08-0110
FCI	5x6 RA Assy	5	RELEASED
	Signal RCP PIP with HDF	52085C	Rev.
Print file	catalog no	metral	customer copy
			sheet 2 of 2